



# SINGLE-CHIP, LI-ION AND LI-POL CHARGER IC WITH AUTONOMOUS USB-PORT AND AC-ADAPTER SUPPLY MANAGEMENT (bqTINY™-II)

#### **FEATURES**

- Small 3 mm × 3 mm MLP Package
- Charges and powers Systems from Either AC Adapter or USB With Autonomous power-Source Selection
- Integrated USB Control With Selectable 100 mA and 500 mA Charge Rates
- Ideal for Low-Dropout Charger Designs for Single-Cell Li-lon or Li-pol Packs in Space Limited portable applications
- Integrated power FET and Current Sensor for Up to 1-A Charge applications From AC Adapter
- Precharge Conditioning With Safety Timer
- power Good (AC Adapter Present) Status Output
- Optional Battery Temperature Monitoring Before and During Charge
- Automatic Sleep Mode for Low-power Consumption

# **APPLICATIONS**

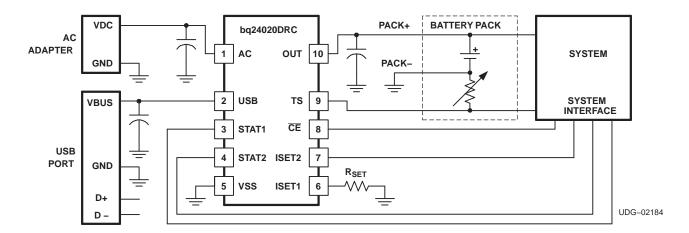
- PDAs, MP3 Players
- Digital Cameras
- Internet appliances
- Smartphones

#### DESCRIPTION

The bqTINY-II series are highly-integrated, flexible Li-lon linear charge and system power management devices for space-limited charger applications. In a single monolithic device, the bqTINY-II offers integrated USB-port and ac-adapter supply management with autonomous power-source selection, power-FET and current-sensor interfaces, high-accuracy current and voltage regulation, charge status, and charge termination.

The bqTINY-II automatically selects the USB-port or the ac-adapter as the power source for the system. In the USB configuration, the host can select from two preset charge rates of 100 mA or 500 mA. In the ac-adapter configuration, an external resistor sets the system or charge current.

The bqTINY-II charges the battery in three phases: conditioning, constant current, and constant voltage. Charge is terminated based on minimum current. An internal charge timer provides a backup safety for charge termination. The bqTINY-II automatically restarts the charge if the battery voltage falls below an internal threshold. The bqTINY-II automatically enters sleep mode when both supplies are removed.



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

#### **DESCRIPTION CONTINUED**

Different versions of the bqTINY-II offer many additional features. These include a temperature-sensor input for detecting hot or cold battery packs, a power-good output  $(\overline{PG})$  indicating the presence of input power, a TTL-level charge-enable input  $(\overline{CE})$  used to disable or enable the charge process, and a TTL-level timer and taper-detect enable input  $(\overline{TTE})$  used to disable or enable the fast-charge timer and charge termination.

#### ORDERING INFORMATION

TJ	CHARGE REGULATION VOLTAGE (V)(1)	OPTIONAL FUNCTIONS <sup>(1)</sup>	FAST-CHARGE TIMER (Hours)	TAPER TIMER	USB TAPER THRESHOLD	PART NUMBER(2)	MARKINGS
	4.2	CE and TS	5	Yes	10% of ISET1 Level	bq24020DRCR	AZS
	4.2	PG and CE	5	Yes	10% of ISET1 Level	bq24022DRCR	AZU
	4.2	CE and TTE	5	Yes	10% of ISET1 Level	bq24023DRCR	AZV
-40°C	4.2	TTE and TS	5	Yes	10% of ISET1 Level	bq24024DRCR	AZW
to 125°C	4.2	CE and TS	7	Yes	10% of ISET1 Level	bq24025DRCR	AZX
120 0	4.2	4.2 TE and TS		No	10% of selected USB charge rate	bq24026DRCR	ANR
	4.2	PG and CE	7	No	10% of selected USB charge rate	bq24027DRCR	ANS

<sup>(1)</sup> The DRC package is available taped and reeled only in quantities of 3,000 devices per reel.

# **Dissipation Ratings**

PACKAGE	$\theta_{JA}$	T <sub>A</sub> < 40°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C
DRC <sup>(1)</sup>	46.87 °C/W	1.5 W	0.021 W/°C

<sup>(1)</sup> This data is based on using the JEDEC High-K board and the exposed die pad is connected to a copper pad on the board. This is connected to the ground plane by a 2×3 via matrix.

# ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

		bq24020, bq24022, bq24023, bq24024 bq24025, bq24026 bq24027	UNIT
Input voltage (2)	AC, $\overline{\text{CE}}$ , ISET1, ISET2, OUT, $\overline{\text{PG}}$ , STAT1, STAT2, $\overline{\text{TE}}$ , TS, $\overline{\text{TTE}}$ , USB	-0.3 to 7.0	V
Output sink/source current	STAT1, STAT2, PG	15	mA
Output current	TS	200	μΑ
Output current	OUT	1.5	Α
Operating free-air temperature	e range, T <sub>A</sub>	-40 to 125	
Junction temperature range, 7	- J	-40 (0 125	°C
Storage temperature, T <sub>stg</sub>		-65 to 150	

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> All voltages are with respect to V<sub>SS</sub>.



# **RECOMMENDED OPERATING CONDITIONS**

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM MAX	UNIT
Supply voltage (from AC input), V <sub>CC</sub>	4.5	6.5	V
Supply voltage (from USB input), V <sub>CC</sub>	4.35	6.5	V
Operating junction temperature range, T <sub>J</sub>	-40	125	°C

## **ELECTRICAL CHARACTERISTICS**

over 0°C ≤ T<sub>J</sub> ≤ 125°C and recommended supply voltage, unless otherwise noted

	PARAMETER	TEST CONDI	TIONS	MIN	TYP	MAX	UNIT
INPUT CU	IRRENT		-1				
I <sub>CC</sub> (V <sub>CC</sub> )	V <sub>CC</sub> current	$V_{CC} > V_{CC(min)}$			1.2	2.0	mA
I <sub>CC(SLP)</sub>	Sleep current	Sum of currents into OUT p	in, V <sub>CC</sub> < V <sub>(SLP)</sub>		2	5	
I <sub>CC(STBY)</sub>	Standby current	CE = High	0°C ≤T <sub>J</sub> ≤ 85°C		1	150	ì
II <sub>B(OUT)</sub>	Input current on OUT pin	Charge DONE	$V_{CC} > V_{CC(MIN)}$			5	^
$II_{B(CE)}$	Input current on CE pin					1	μΑ
$II_{B(TTE)}$	Input bias current on TTE pin					1	ī
II <sub>B(TE)</sub>	Input bias current on TE pin					1	ì
VOLTAGE	REGULATION V <sub>O(REG)</sub> + V <sub>(DO-MAX)</sub> S	≤ V <sub>CC</sub> , I <sub>(TERM)</sub> < I <sub>O(OUT)</sub> ≤ 1 A	·				
$V_{O(REG)}$	Output voltage,				4.20		V
	Valtage regulation courses.	T <sub>A</sub> = 25°C		-0.35%		0.35%	
	Voltage regulation accuracy			-1%		1%	
V <sub>(DO)</sub>	AC dropout voltage $(V_{(AC)}-V_{(OUT)})$	$V_{O(OUT)} = V_{O(REG)}$ $V_{O(REG)} + V_{(DO-MAX)}) \le V_{CC}$	$I_{O(OUT)} = 1A$		350	500	l
V	USB dropout voltage	$V_{O(OUT)} = V_{O(REG)}$ $V_{O(REG)} + V_{(DO-MAX)}) \le V_{CC}$	ISET2 = High		350	500	mV
$V_{(DO)}$	$(V_{(USB)} - V_{(OUT)})$	1 0			60	100	ı
CURRENT	T REGULATION		1				
I <sub>O(OUT)</sub>	AC output current range <sup>(1)</sup>	$V_{I(OUT)} > V_{(LOWV)}$ $V_{I(AC)} - V_{I(OUT)} > V_{(DO-MAX)}$	V <sub>CC</sub> ≥ 4.5 V	50		1000	
	LICP systems are reading.	$V_{CC(MIN)} \ge 4.5 \text{ V}$ $V_{USB} - V_{I(OUT)} > V_{(DO-MAX)}$	$V_{I(OUT)} > V_{(LOWV)}$ ISET2 = Low	80		100	mA
I <sub>O(OUT)</sub>	USB output current range	$V_{CC(MIN)} \ge 4.5 \text{ V}$ $V_{USB} - V_{I(OUT)} > V_{(DO-MAX)}$	$V_{I(OUT)} > V_{(LOWV)}$ ISET2 = High	400		500	ı
V <sub>(SET)</sub>	Output current set voltage	Voltage on ISET1 pin, $V_{CC} \ge V_{I(OUT)} > V_{(LOWV)}$ , $V_{IN} - V_{I(OUT)} > V_{I(OWV)}$		2.463	2.500	2.538	٧
		$50 \text{ mA} \le I_{O(OUT)} \le 1 \text{ A}$	307	322	337		
$K_{(SET)}$	Output current set factor	10 mA ≤ I <sub>O(OUT)</sub> < 50 mA		296	320	346	
		1 mA ≤ I <sub>O(OUT)</sub> < 10 mA		246	320	416	1

$$I_{O(OUT)} = \frac{\left(K_{(SET)} \times V_{(SET)}\right)}{R_{SET}}$$



# **ELECTRICAL CHARACTERISTICS (continued)**

over  $0^{\circ}C \le T_{J} \le 125^{\circ}C$  and recommended supply voltage, unless otherwise noted

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
PRECHAR	GE AND SHORT-CIRCUI	T CURREN	T REGULATION				
V <sub>(LOWV)</sub>	Precharge to fast-charge transition threshold	e	Voltage on OUT pin	2.8	3.0	3.2	V
	Deglitch time for fast-chaprecharge transition	arge to	$V_{CC(MIN)} \ge 4.5 \text{ V}, t_{FALL} = 100 \text{ ns}, 10 \text{ mV}$ overdrive, $V_{I(OUT)}$ decreasing below threshold	250	375	500	ms
I <sub>O(PRECHG)</sub>	Precharge range (2)		$0 \text{ V} < V_{\text{I(OUT)}} < V_{\text{(LOWV)}}, t < t_{\text{(PRECHG)}}$	5		100	mA
V <sub>(PRECHG)</sub>	Precharge set voltage			240	255	270	mV
CHARGE T	TAPER AND TERMINATION	ON DETEC	TION				
I <sub>(TAPER)</sub>	Charge taper detection r	ange <sup>(3)</sup>	$V_{I(OUT)} > V_{(RCH)}, t < t_{(TAPER)}$	5		100	
	USB-100 charge taper detection level bq24026		$V_{I(OUT)} > V_{(RCH)}$ , ISET2 = Low	6.5	9	11	mA
	USB-500 charge taper detection level	bq24026	$V_{I(OUT)} > V_{(RCH)}$ , ISET2 = High	32	44	55	
V <sub>(TAPER)</sub>	Charge taper detection s	set voltage	Voltage on ISET1 pin, $V_{O(REG)} = 4.2 \text{ V}$ , $V_{I(OUT)} > V_{(RCH)}$ , $t < t_{(TAPER)}$	235	250	265	.,
V <sub>(TERM)</sub>	Charge termination dete set voltage (4)	ction	Voltage on ISET1 pin, $V_{O(REG)} = 4.2 \text{ V}$ , $V_{I(OUT)} > V_{(RCH)}$	11	18	25	mV
t <sub>(TPRDET)</sub>	Deglitch time for TAPER	detection	V <sub>CC(MIN)</sub> ≥ 4.5 V, t <sub>FALL</sub> = 100 ns charging current increasing or decreasing above and below, 10 mV overdrive	250	375	500	ms
t <sub>(TRMDET)</sub>	Deglitch time for termination detection		$V_{CC(MIN)} \ge 4.5 \text{ V}, t_{FALL} = 100 \text{ ns charging}$ current decreasing below, 10 mV overdrive	250	375	500	
TEMPERA*	TURE SENSE COMPARA	ATOR	-				
V <sub>(HTF)</sub>	High-voltage threshold		PTC thermistor	2.475	2.500	2.525	V
V <sub>(LTF)</sub>	Low-voltage threshold		PTC thermistor	0.485	0.500	0.515	V
I <sub>(TS)</sub>	Current source			96	102	108	μΑ
t <sub>(DEGL)</sub>	Deglitch time for tempera	ature fault		250	375	500	ms

(2) 
$$I_{O(PRECHG)} = \frac{\left(K_{(SET)} \times V_{(PRECHG)}\right)}{R_{SET}}$$
(3) 
$$I_{O(TAPER)} = \frac{\left(K_{(SET)} \times V_{(TAPER)}\right)}{R_{SET}}$$
(4) 
$$I_{O(TERM)} = \frac{\left(K_{(SET)} \times V_{(TERM)}\right)}{R_{SET}}$$

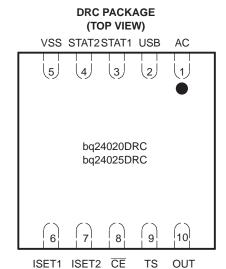


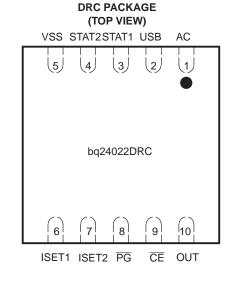
# **ELECTRICAL CHARACTERISTICS (continued)**

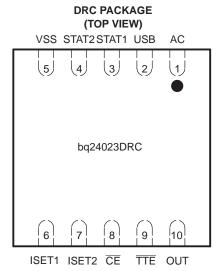
over  $0^{\circ}C \le T_{J} \le 125^{\circ}C$  and recommended supply voltage, unless otherwise noted

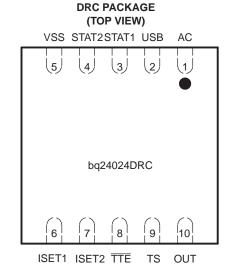
	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BATTERY	RECHARGE THRESH	IOLD					
V <sub>RCH</sub>	Recharge threshold			V <sub>O(REG)</sub> - 0.115	V <sub>O(REG)</sub> -0.10	V <sub>O(REG)</sub> - 0.085	V
t <sub>(DEGL)</sub>	Deglitch time for rech	narge detect	V <sub>CC(MIN)</sub> ≥ 4.5 V, t <sub>FALL</sub> = 100 ns decreasing below or increasing above threshold, 10 mV overdrive	250	375	500	ms
	STAT1, STAT2, and	PG OUTPUTS	3				
$V_{OL}$	Low-level output satu	ration voltage	$I_O = 5 \text{ mA}$			0.25	V
	ISET2, CHARGE EN	ABLE (CE), TI	MER AND TERMINATION ENABLE (TTE), AND	TIMER ENA	BLE (TE) I	NPUTS	
$V_{\text{IL}}$	Low-level input voltag	ge	$I_{IL} = 10 \mu A$	0		0.4	V
$V_{IH}$	High-level input voltage		$I_{IL} = 20 \mu A$	1.4			V
IIL	CE, TE or TTE low-le input current	evel		-1			
II <sub>H</sub>	CE, TE or TTE high-l input current	evel				1	μΑ
I <sub>IL</sub>	ISET2 low-level input current		I <sub>ISET2</sub> = 0	-20			
I <sub>IH</sub>	ISET2 high-level inpu	ut current	I <sub>ISET2</sub> = V <sub>CC</sub>			40	
I <sub>IH</sub>	ISET2 high-Z input co	urrent				1	V
TIMERS							
$t_{(PRECHG)}$	Precharge time			1,584	1,800	2,016	
t <sub>(TAPER)</sub>	Taper time	bq24020 bq24022 bq24023 bq24024 bq24025		1,584	1,800	2,016	
<sup>t</sup> (CHG)	bo	bq24020 bq24022 bq24023 bq24024		15,840	18,000	20,160	S
,		bq24025 bq24026 bq24027		22,176	25,200	28,224	
I <sub>(FAULT)</sub>	Timer fault recovery	current			200		μΑ
SLEEP CO	MPARATOR						
$V_{(SLP)}$	Sleep-mode entry threshold voltage		$2.3 \text{ V} \leq \text{V}_{\text{I}(\text{OUT})} \leq \text{V}_{\text{O}(\text{REG})}$			$V_{CC} \le V_{I(OUT)} + 80 \text{ mV}$	V
V <sub>(SLPEXIT)</sub>	Sleep mode exit threshold voltage		$2.3 \text{ V} \leq \text{V}_{\text{I(OUT)}} \leq \text{V}_{\text{O(REG)}}$	V <sub>CC</sub> ≥ V <sub>I(OUT)</sub> +190mV			V
	Sleep mode deglitch time		AC and USB decreasing below threshold, t <sub>FALL</sub> = 100 ns, 10 mV overdrive	250	375	500	ms
THERMAL	SHUTDOWN THRESH	HOLDS					
T <sub>(SHTDWN)</sub>	Thermal trip threshold	d			165		°C
	Thermal hysteresis				15		
UNDERVO	LTAGE LOCKOUT			•			
V <sub>(UVLO)</sub>	Undervoltage lockout	i	Decreasing V <sub>CC</sub>	2.4	2.5	2.6	V
	Hysteresis				27		mV

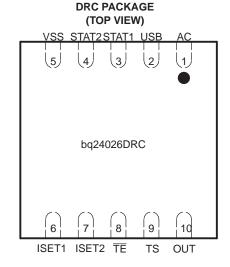


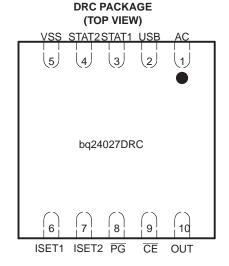


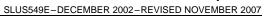












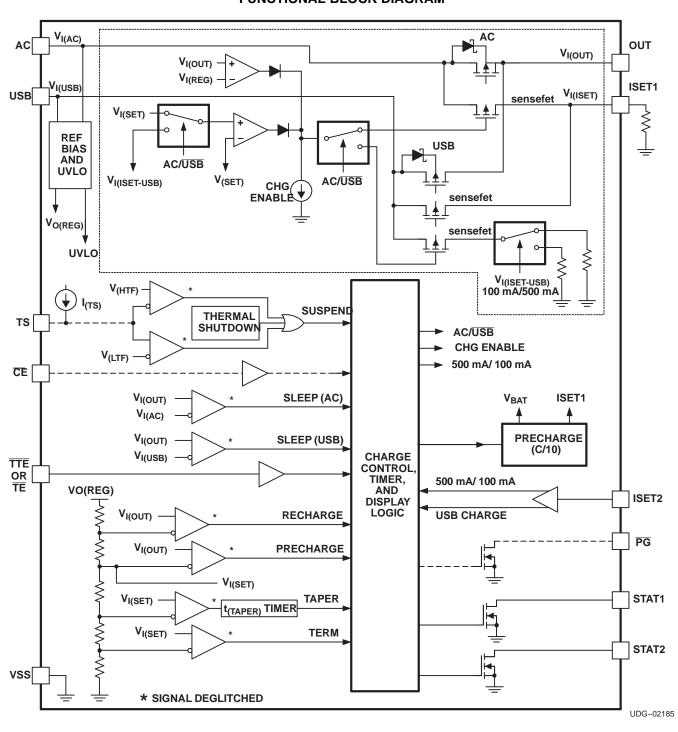


### **Terminal Functions**

	TERMINA	L					
NAME	bq24020 bq24025	bq24022 bq24027	bq24023	bq24024	bq24026	1/0	DESCRIPTION
AC	1	1	1	1	1	I	AC charge input voltage
CE	8	9	8	-	-	I	Charge enable input (active low)
ISET1	6	6	6	6	6	I	Charge current set point for AC input and precharge and taper set point for both AC and USB
ISET2	7	7	7	7	7	I	Charge current set point for USB port (high=500 mA, low=100 mA, hi-z = disable USB charge)
OUT	10	10	10	10	10	0	Charge current output
PG	-	8	-	-	-	0	powergood status output (active low)
STAT1	3	3	3	3	3	0	Charge status output 1 (open-drain)
STAT2	4	4	4	4	4	0	Charge status output 2 (open-drain)
TE	-	-	-	-	8	I	Timer enable input (active low)
TS	9	-	-	9	9	I	Temperature sense input
TTE	-	-	9	8	-	I	Timer and termination enable input (active low)
USB	2	2	2	2	2	I	USB charge input voltage
VSS	5	5	5	5	5	-	Ground input
Exposed Thermal Pad	pad	pad	pad	pad	pad	-	There is an internal electrical connection between the exposed thermal pad and VSS pin of the device. The exposed thermal pad must be connected to the same potential as the VSS pin on the printed circuit board. <b>Do not use the thermal pad as the primary ground input for the device.</b> VSS pin must be connected to ground at all times



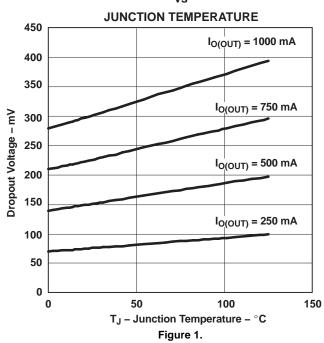
#### **FUNCTIONAL BLOCK DIAGRAM**





### TYPICAL CHARACTERISTICS

AC DROPOUT VOLTAGE vs



The bqTINY-II supports a precision Li-lon, Li-pol charging system suitable for single-cell packs. Figure 3 shows a typical charge profile, application circuit and Figure 4 shows an operational flow chart.

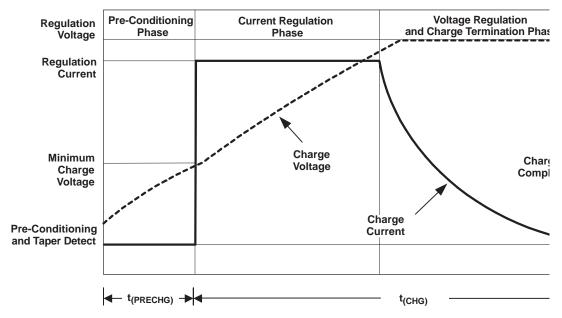
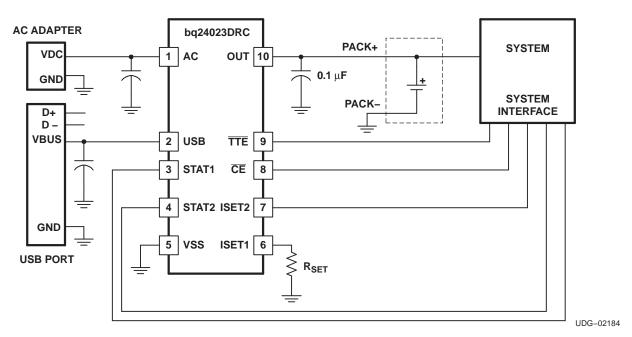


Figure 2. Typical Charging Profile

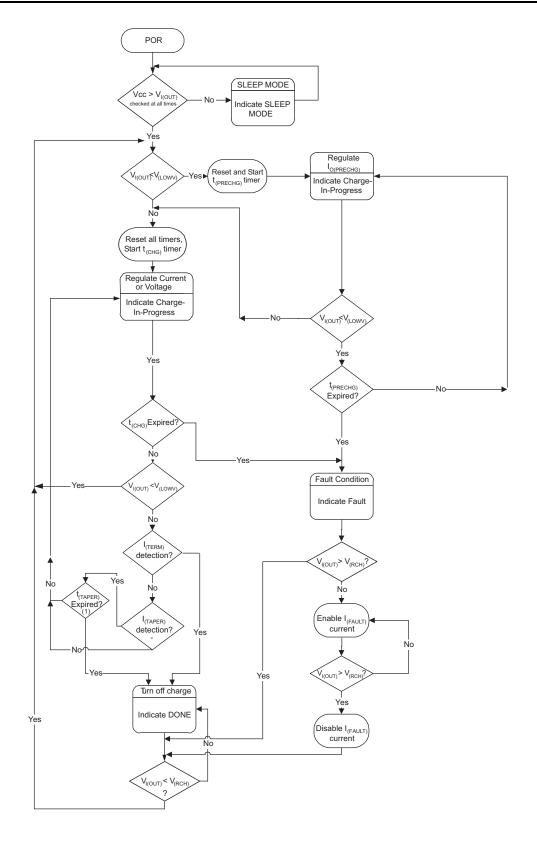


# **FUNCTIONAL DESCRIPTION**



**Figure 3. Typical Application Circuit** 





(1) t<sub>(TAPER)</sub> does not apply to bq24026/7

Figure 4. Operational Flow Chart

### **AUTONOMOUS POWER SOURCE SELECTION**

As default, the bqTINY-II attempts to charge from the AC input. If AC input is not present, the USB is selected. If both inputs are available, the AC adapter has the priority. See for details.



Figure 5. Typical Charging Profile

# TEMPERATURE QUALIFICATION (bq24020, bq24024, bq24025, and bq24026 only)

The bqTINY-II continuously monitors battery temperature by measuring the voltage between the TS and VSS pins. An internal current source provides the bias for common  $10\text{-k}\Omega$  negative-temperature coefficient thermistors (NTC) (see Figure 6). The device compares the voltage on the TS pin with the internal  $V_{(LTF)}$  and  $V_{(HTF)}$  thresholds to determine if charging is allowed. If a temperature outside the  $V_{(LTF)}$  and  $V_{(HTF)}$  thresholds is detected, the device immediately suspends the charge by turning off the power FET and holding the timer value (i.e. timers are NOT reset). Charge is resumed when the temperature returns within the normal range.

The allowed temperature range for a 103AT-type thermistor is 0°C to 45°C. However the user may modify these thresholds by adding two external resistors. See Figure 7.

#### **BATTERY PRE-CONDITIONING**

If the battery voltage falls below the  $V_{(LOWV)}$  threshold during a charge cycle, the bqTINY-II applies a precharge current,  $I_{O(PRECHG)}$ , to the battery. This feature revives deeply discharged cells. The resistor connected between the ISET1 and  $V_{SS}$ ,  $R_{SET}$ , determines the precharge rate. The  $V_{(PRECHG)}$  and  $K_{(SET)}$  parameters are specified in the specifications table. Note that this applies to both AC and USB charging.

$$I_{O (PRECHG)} = \frac{V_{(PRECGH)} - K_{(SET)}}{R_{SET}}$$
 (1)

The bqTINY-II activates a safety timer,  $t_{(PRECHG)}$ , during the conditioning phase. If  $V_{(LOWV)}$  threshold is not reached within the timer period, the bqTINY-II turns off the charger and asserts a FAULT code on the STATx pins. Please refer to the *TIMER FAULT RECOVERY* section for additional details.

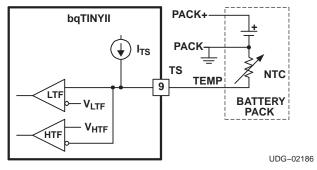


Figure 6. Temperature Sensing Configuration

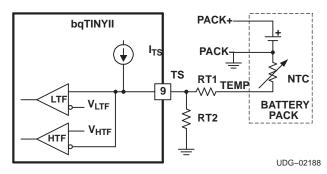


Figure 7. Temperature Sensing Thresholds



### **BATTERY CHARGE CURRENT**

The bqTINY-II offers on-chip current regulation with a programmable set point. The resistor connected between the ISET1 and  $V_{SS}$ ,  $R_{SET}$ , determines the AC charge rate. The  $V_{(SET)}$  and  $K_{(SET)}$  parameters are specified in the specifications table.

$$I_{O(OUT)} = \frac{\left(K_{(SET)} \times V_{(SET)}\right)}{R_{SET}}$$
(2)

When charging from a USB port, the host controller has the option of selecting either a 100-mA or a 500-mA charge rate using the ISET2 pin. A low-level signal sets the current at 100 mA, and a high-level signal sets the current at 500 mA. A high-Z input disables USB charging

#### **BATTERY VOLTAGE REGULATION**

The voltage regulation feedback is through the OUT pin. This input is tied directly to the positive side of the battery pack. The bqTINY-II monitors the battery-pack voltage between the OUT and VSS pins. When the battery voltage rises to the  $V_{O(REG)}$  threshold, the voltage-regulation phase begins and the charging current begins to taper down.

As a safety backup, the bqTINY-II also monitors the charge time. If the charge is not terminated within the time period specified by t<sub>(CHG)</sub>, the bqTINY-II turns off the charger and asserts a FAULT code on the STATx pins. Please refer to the *TIMER FAULT RECOVERY* section for additional details.

# CHARGE TAPER DETECTION, TERMINATION AND RECHARGE

The bqTINY-II monitors the charging current during the voltage-regulation phase. When the taper threshold,  $I_{(TAPER)}$ , is detected, the bqTINY-II initiates the taper timer,  $t_{(TAPER)}$ . Charge is terminated after the timer expires. The resistor connected between the ISET1 and  $V_{SS}$ ,  $R_{SET}$ , determines the taper detection level. The  $V_{(TAPER)}$  and  $K_{(SET)}$  parameters are specified in the specifications table. Note that this applies to both AC and USB charging.

$$I_{(TAPER)} = \frac{V_{(TAPER)} \times K_{(SET)}}{R_{SET}}$$
(3)

The bqTINY-II resets the taper timer if the charge current rises above the taper threshold, I<sub>(TAPER)</sub>.

In addition to taper-current detection, the bqTINY-II terminates charge if the charge current falls below the  $I_{(TERM)}$  threshold. This feature allows quick recognition of a battery-removal condition, or insertion of a fully charged battery. Note that the charge timer and taper timer are bypassed for this feature. The resistor connected between the ISET1 and  $V_{SS}$ ,  $R_{SET}$ , determines the taper detection level. The  $V_{(TERM)}$  and  $K_{(SET)}$  parameters are specified in the specifications table. Note that this applies to both AC and USB charging.

$$I_{(TERM)} = \frac{V_{(TERM)} \times K_{(SET)}}{R_{SET}}$$
(4)

After charge termination, the bqTINY-II re-starts the charge when the voltage on the OUT pin falls below the  $V_{(RCH)}$  threshold. This feature keeps the battery at full capacity at all times.

#### Note ON bg24026 AND bg24027

The bq24026 and bq24027 monitor the charging current during the voltage-regulation phase. Once the taper threshold,  $I_{(TAPER)}$ , is detected, the bq24026/27 terminates the charge. There is no taper timer ( $t_{(TAPER)}$ ) for this version.

The resistor connected between the ISET1 and  $V_{SS}$ ,  $R_{SET}$ , determines the taper-detect level for AC input. For USB charge, taper level is fixed at 10% of the 100- or 500-mA charge rate.

Also note that there is I<sub>(TERM)</sub> detection in the bq24026 and the bq24027.

#### **SLEEP MODE**

The bqTINY-II enters low-power sleep mode if both AC and USB are removed from the circuit. This feature prevents draining the battery in the absence of input supply.

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#### **CHARGE STATUS OUTPUTS**

The open-drain STAT1 and STAT2 outputs indicate various charger operations as shown in the following table. These status pins can be used to drive LEDs or communicate to the host processor. Note that OFF indicates the open-drain transistor is turned off.

Table 1. Status Pins Summary<sup>(1)</sup>

CHARGE STATE	STAT1	STAT2
Precharge in progress	ON	ON
Fast charge in progress	ON	OFF
Charge done	OFF	ON
Charge suspend (temperature)	OFF	OFF
Timer fault	OFF	OFF
Sleep mode	OFF	OFF

<sup>(1)</sup> OFF means the open-drain output transistor on the STAT1 and STAT2 pins is in an off state.

#### **PG** OUTPUT

The open-drain  $\overline{PG}$  (power Good) indicates when the AC adapter is present. The output turns ON when a valid voltage is detected. This output is turned off in the sleep mode. The  $\overline{PG}$  pin can be used to drive an LED or to communicate to the host processor.

# **CE INPUT (CHARGE ENABLE)**

The  $\overline{\text{CE}}$  digital input is used to disable or enable the charge process. A low-level signal on this pin enables the charge. A high-level signal disables the charge, and places the device in a low-power mode. A high-to-low transition on this pin also resets all timers and timer fault conditions. Note that this applies to both AC and USB charging.

# TTE INPUT (TIMER AND TERMINATION ENABLE)

The TTE digital input is used to disable or enable the fast-charge timer and charge-taper detection. A low-level signal on this pin enables the fast-charge timer and taper timer, and a high-level signal disables this feature. Note that this applies to both AC and USB charging.

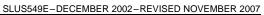
#### THERMAL SHUTDOWN AND PROTECTION

The bqTINY-II monitors the junction temperature,  $T_J$ , and suspends charging if  $T_J$  exceeds  $T_{(SHTDWN)}$ . Charging resumes when  $T_J$  falls approximately 15°C below  $T_{(SHTDWN)}$ .

#### **TE INPUT (TIMER ENABLED)**

The TE digital input is used to disable or enable the fast-charge timer. A low-level signal on this pin enables the fast-charge timer and a high-level signal disables this feature.

Note that this applies to both AC and USB charging.





#### TIMER FAULT RECOVERY

As shown in Figure 4, the bqTINY-II provides a recovery method to deal with timer-fault conditions. The following discussion summarizes this method:

Condition #1: The charge voltage is above the recharge threshold (V<sub>(RCH)</sub>), and a timeout fault occurs

**Recovery method:** bqTINY-II waits for the battery voltage to fall below the recharge threshold. This could happen as a result of a load on the battery, self-discharge or battery removal. When the battery voltage falls below the recharge threshold, the bqTINY-II clears the fault and starts a new charge cycle. Toggling POR,  $\overline{\text{CE}}$ , or  $\overline{\text{TTE}}$  also clears the fault.

Condition #2: The charge voltage is below the recharge threshold (V<sub>(RCH)</sub>), and a timeout fault occurs

**Recovery method:** In this scenario, the bqTINY-II applies the  $I_{(FAULT)}$  current. This small current is used to detect a battery-removal condition and remains on as long as the battery voltage stays below the recharge threshold. If the battery voltage goes above the recharge threshold, then the bqTINY-II disables the  $I_{(FAULT)}$  current and executes the recovery method described for condition #1. When the battery voltage falls below the recharge threshold, the bqTINY-II clears the fault and starts a new charge cycle. Toggling POR,  $\overline{CE}$ , or  $\overline{TTE}$  also clears the fault.

#### APPLICATION INFORMATION

#### THERMAL CONSIDERATIONS

The bqTINY-II is packaged in a thermally enhanced MLP package. The package includes a thermal pad to provide an effective thermal contact between the device and the printed circuit board (PCB). Full PCB design guidelines for this package are provided in the application note entitled, QFN/SON PCB Attachment Application Note (TI Literature Number SLUA271).

The most common measure of package thermal performance is thermal impedance ( $\theta_{JA}$ ) measured (or modeled) from the device junction to the air surrounding the package surface (ambient). The mathematical expression for  $\theta_{JA}$  is:

$$\theta_{\mathsf{JA}} = \frac{\mathsf{T}_{\mathsf{J}} - \mathsf{T}_{\mathsf{A}}}{\mathsf{P}} \tag{5}$$

Where:

- T<sub>J</sub> = device junction temperature
- T<sub>A</sub> = ambient temperature
- P = device power dissipation

Factors that can greatly influence the measurement and calculation of  $\theta_{1A}$  include:

- · whether or not the device is board mounted
- trace size, composition, thickness, and geometry
- orientation of the device (horizontal or vertical)
- volume of the ambient air surrounding the device under test and airflow\_lus549
- whether other surfaces are in close proximity to the device being tested

The device power dissipation, P, is a function of the charge rate and the voltage drop across the internal power FET. It can be calculated from the following equation:

$$P = (V_{IN} - V_{I(BAT)}) \times I_{O(OUT)}$$
(6)

Due to the charge profile of Li-xx batteries, the maximum power dissipation is typically seen at the beginning of the charge cycle when the battery voltage is at its lowest. See Figure 2.

#### **PCB LAYOUT CONSIDERATIONS**

It is important to pay special attention to the PCB layout. The following provides some guidelines:

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- To obtain optimal performance, the decoupling capacitor from V<sub>CC</sub> to V<sub>SS</sub> and the output filter capacitors from OUT to VSS should be placed as close as possible to the bqTINY, with short trace runs to both signal and V<sub>SS</sub> pins.
- All low-current V<sub>SS</sub> connections should be kept separate from the high-current charge or discharge paths from the battery. Use a single-point ground technique incorporating both the small-signal ground path and the power-ground path.
- The BAT pin is the voltage feedback to the device. It should be connected with its trace as close to the battery pack as possible.
- The high-current charge paths into IN and from the OUT pins must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces.
- The bqTINY-II is packaged in a thermally-enhanced MLP package. The package includes a thermal pad to
  provide an effective thermal contact between the device and the printed circuit board (PCB). Full PCB design
  guidelines for this package are provided in the application note entitled: QFN/SON PCB Attachment
  Application Note (TI Literature No. SLUA271).

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
BQ24020DRCR	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	AZS
BQ24020DRCR.B	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	AZS
BQ24022DRCR	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	AZU
BQ24022DRCR.B	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	AZU
BQ24023DRCR	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AZV
BQ24023DRCR.B	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	AZV
BQ24024DRCR	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	AZW
BQ24024DRCR.B	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	AZW
BQ24025DRCR	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AZX
BQ24025DRCR.B	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	AZX
BQ24026DRCR	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ANR
BQ24026DRCR.B	Active	Production	VSON (DRC)   10	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ANR
BQ24027DRCR	Obsolete	Production	VSON (DRC)   10	-	-	Call TI	Call TI	-40 to 85	ANS

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



# **PACKAGE OPTION ADDENDUM**

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Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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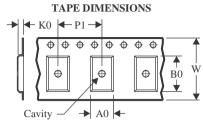
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# **PACKAGE MATERIALS INFORMATION**

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# TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ24020DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24022DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24023DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24024DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24025DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24026DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2



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# \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ24020DRCR	VSON	DRC	10	3000	367.0	367.0	35.0
BQ24022DRCR	VSON	DRC	10	3000	367.0	367.0	35.0
BQ24023DRCR	VSON	DRC	10	3000	367.0	367.0	35.0
BQ24024DRCR	VSON	DRC	10	3000	367.0	367.0	35.0
BQ24025DRCR	VSON	DRC	10	3000	367.0	367.0	35.0
BQ24026DRCR	VSON	DRC	10	3000	367.0	367.0	35.0

3 x 3, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD

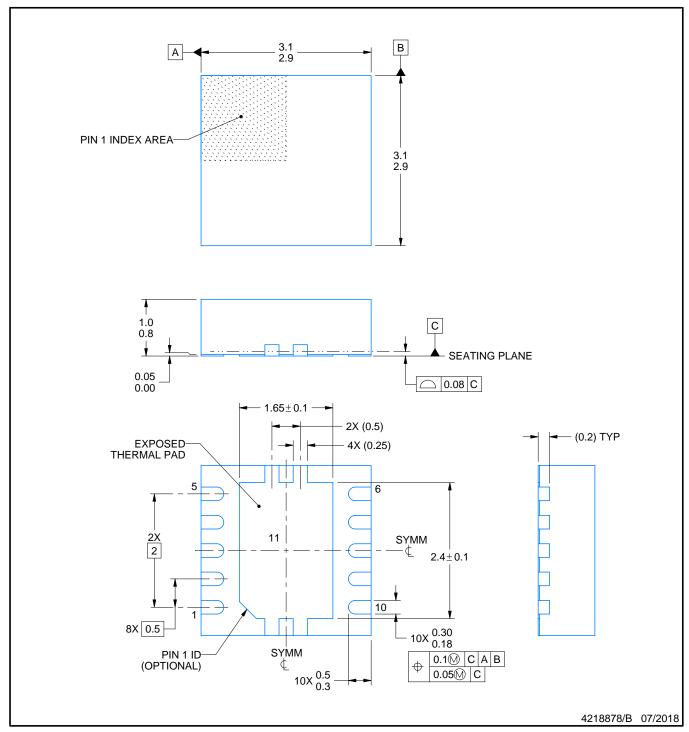
This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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PLASTIC SMALL OUTLINE - NO LEAD

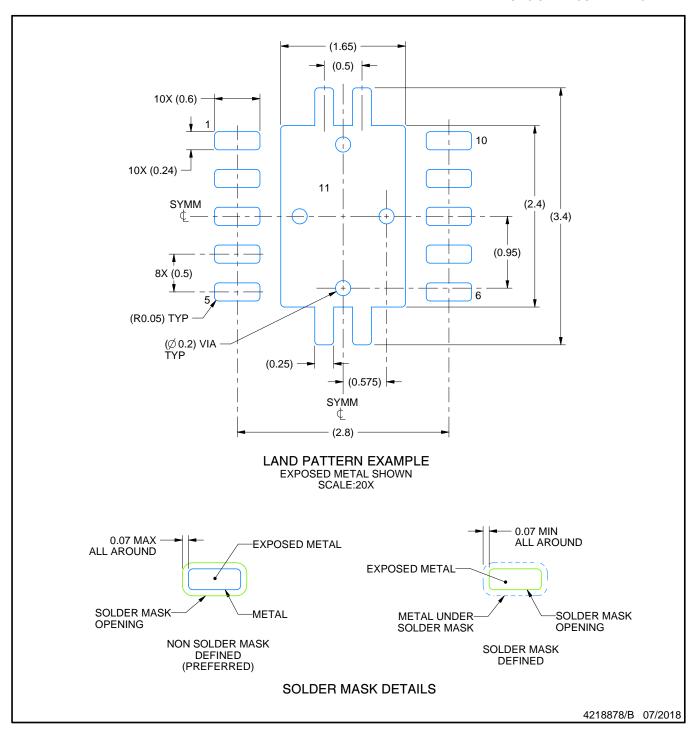


#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



PLASTIC SMALL OUTLINE - NO LEAD

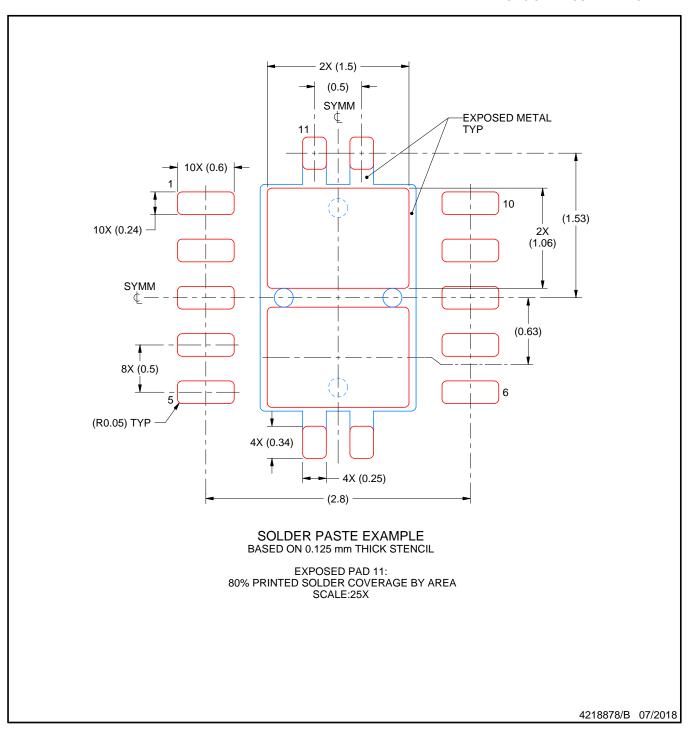


NOTES: (continued)

- 4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- 5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



PLASTIC SMALL OUTLINE - NO LEAD



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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